GSM6320TF

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Preliminary Specification

60V N-Channel MOSFET

Absolute Maximum Ratings (T_A=25°C unless otherwise specified)

Symbol	Parameter		Value	Unit	
V _{DS}	Drain-Source Voltage		60	V	
V _{GS}	Gate-Source Voltage		±20	V	
lο	Continuous Drain Current (Silicon Limited)	T _C =25°C	194		
		T _C =100°C	122	A	
	Continuous Drain Current (Package Limited)		120		
I _{DM}	Pulsed Drain Current ¹		400	Α	
P _D	Power Dissipation	T _C =25°C	208	w	
		T _C =100°C	83		
R _{eJC}	Thermal Resistance-Junction to Case		0.6	°C/W	
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient		62	°C/W	
TJ	Operating Junction Temperature Range		-55 to +150	$^{\circ}\!\mathbb{C}$	
Tstg	Storage Temperature Range		-55 to +150	$^{\circ}\!\mathbb{C}$	

NOTE:

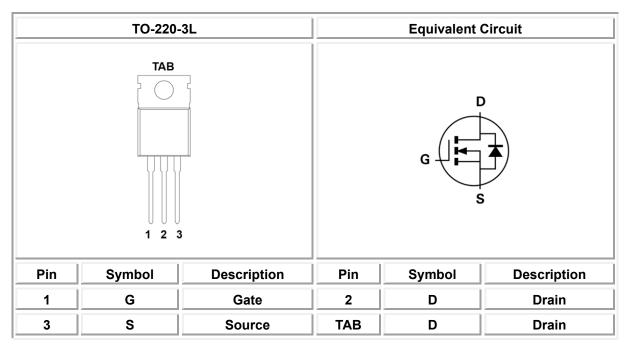
Electrical Characteristics (T_A=25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit		
	Static							
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	60			V		
I _{DSS}	Drain-Source Leakage Current	V _{DS} =60V, V _{GS} =0V			1	uA		
Igss	Gate-Source Leakage Current	V _{DS} =0V, V _{GS} =±20V			±100	nA		
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	1.2		2.5	V		
Б	Drain-Source On-Resistance	V _{GS} =10V, I _D =20A			2.3	mΩ		
R _{DS(on)}		V _{GS} =4.5V, I _D =10A			3.5			
VsD	Diode Forward Voltage	V _{GS} =0V, I _S =1A			1.0	V		



^{1.} Pulse width limited by maximum junction temperature.

Packages & Pin Assignments





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